

FORM PTO-1449
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APPLICANT
Margaret S. FyfieldFILING DATE
December 6, 2000GROUP
2813

U.S. PATENT DOCUMENTS

EXAM. INIT.	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB- CLASS	FILING DATE IF APPRO- PRIATE

FOREIGN PATENT DOCUMENTS

DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB- CLASS	TRANS- LATION
					YES NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

VR		Gary Shade and Kendall Scott Wills, <i>Photoemission Microscopy</i> , 1997 ASM International, pp. 181-182.
VR		B. Bossmann, P. Baurechmidt, K. Hussey, and E. Black, <i>Failure Analysis Techniques with the Confocal Laser Scanning Microscope</i> , ISTFA '92: The 18 th International Symposium for Testing & Failure Analysis, October 1992, pp. 351-361.
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		TW. Joseph, A.L. Berry, B. Bossman, <i>Infrared Laser Microscopy of Structures on Heavily Doped Silicon</i> , ISTFA '92: The 18 th International Symposium for Testing & Failure Analysis, October 1992, pp. 1-7.
		D.L. Barton, P. Tangyunyong, J.M. Soden, A.Y. Liang, F.J. Low, A.N. Zaptatin, K. Shivanandan, and G. Donohoe, <i>Infrared Light Emission from Semiconductor Devices</i> , Proceedings of the 22 nd International Symposium for Testing and Failure Analysis, November 1996, pp. 9-17.
		Chun-Cheng Tsao, Steven, Kasapi, and Kurt Hurley, <i>Backside waveform probing of CMOS devices using infrared laser at wavelength of 1064 nm</i> , 6 pages.
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		Kendall Scott Wills, Terri Lewis, Greg Bilus, Hai Hoang, <i>Optical Beam Induced Current Applications for Failure Analysis of VLSI Devices</i> , 1997 ASM International, pp. 21-26.
		Yeoh Eng Hong and Martin Tay Tiong We, <i>The application of novel Failure Analysis Techniques for Advanced Multi-Layered CMOS devices</i> , 6 pages.
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		Said F. Al-sarawi, <i>Solder Bump Bonding</i> , Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March 1997, 1 page.

EXAMINER

DATE CONSIDERED

8/10/05

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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